

## REMARKS

Claims 28-39 are currently pending. Claims 28-33 have been canceled herein. Claims 34-37 are amended herein. Reconsideration and allowance of the remaining Claims are respectfully requested.

### 112 Rejections

Claims 30-39 are rejected under 35 USC 112 second paragraph. The Claims have been amended herein to obviate the rejections under 35 USC 112 second paragraph. Consequently, the applicant respectfully submits that the 112 rejection of Claims 30-39 should be withdrawn.

### 102 Rejections

Claims 33-39 are rejected under 35 U.S.C. § 102(a) as being anticipated by Evans et al. (U.S. Patent No. 5,897,424). Claim 33 has been canceled and its subject matter incorporated into new independent Claim 34. The remaining Claims 35-39 depend from independent Claim 34. Applicants have reviewed the cited references and respectfully submit that the present invention as is recited in Claims 34-39 are neither anticipated nor rendered obvious (U.S. Patent No. 5,897,424).

The Examiner is respectfully directed to independent Claim 34 which recites that an embodiment of the present invention is directed to a polishing apparatus comprising:

... a carrier overlying the polishing pad, wherein  
the polishing platen is further characterized as  
having a tapered region, and wherein the  
peripheral region of the polishing pad overlies  
the tapered region.

Claims 35-39 depend from independent Claim 34 and recite further features of the claimed invention.

Evans et al. does not anticipate or render obvious a polishing apparatus that includes a polishing platen, a polishing pad overlying the polishing platen and a carrier overlying the polishing pad and wherein the polishing platen is characterized by "a tapered region, and wherein the peripheral region of the polishing pad overlies the tapered region." Evans only shows a renewable polishing lap. Nowhere in the Evans et al. reference is there shown or suggested a polishing apparatus that includes both a carrier overlying a polishing pad and a polishing platen that has a tapered region that is overlain by a peripheral region of a polishing pad as is recited in Claim 34. Consequently the Applicants' invention as set forth in Claims 34-39 are neither anticipated nor rendered obvious by Evans et al.

Therefore, Applicants respectfully submit that Evans et al. does not anticipate or render obvious the present Claimed invention as is recited in independent Claim 34 and as such Claim 34 traverses the Examiners basis for rejection under 35 U.S.C. 102(a). Accordingly, Applicants submit that Claim 34 is in condition for allowance. In addition, Evans et al. does not anticipate or render obvious the present invention as is recited in Claims 35-39 which depends from independent Claim 34, and that Claims 35-39 are in condition for allowance as being dependent on an allowable base claim.

Claims 33, 35 and 36 are rejected under 35 U.S.C. § 102(b) as being anticipated by Yu et al. (U.S. Patent No. 5,435,772). Claim 33 has been canceled and its subject matter incorporated into new independent Claim 34. Applicants have reviewed the cited references and respectfully submit that the present invention as is recited in Claims 35 and 36 dependent on Claim 34 are neither anticipated nor rendered obvious (U.S. Patent No. 5,435,772).

The Examiner is respectfully directed to independent Claim 34 which recites that an embodiment of the present invention is directed to a polishing apparatus comprising:

...a carrier overlying the polishing pad, wherein  
the polishing platen is further characterized as  
having a tapered region, and wherein the  
peripheral region of the polishing pad overlies  
the tapered region.

Claims 35 and 36 depend from independent Claim 34 and recite further features of the claimed invention.

Yu does not anticipate or render obvious a polishing apparatus that includes a polishing platen, a polishing pad overlying the polishing platen, a carrier overlying the polishing pad and wherein the polishing platen is characterized by “a tapered region, and wherein the peripheral region of the polishing pad overlies the tapered region.” Yu only shows a method of polishing a semiconductor substrate. Nowhere in the Yu reference is there shown or suggested a polishing apparatus that includes both a carrier overlying a polishing pad and a polishing platen that has a tapered region that is overlain by a peripheral region of a polishing pad as is recited in Claim 34. Consequently the Applicants’ invention as set forth in Claims 34-39 are neither anticipated nor rendered obvious by Evans et al.

Therefore, Applicants respectfully submit that Yu does not anticipate or render obvious the present Claimed invention as is recited in independent Claim 34 and as such Claim 34 traverses the Examiners basis for rejection under 35 U.S.C. 102(b). Accordingly, Applicants submit that Claim 34 is in condition for allowance. In addition, Yu does not anticipate or render obvious the present invention as is recited in Claims 35 and 36 which depend from independent Claim 34, and that Claims 35 and 36 are in condition for allowance as being dependent on an allowable base claim.

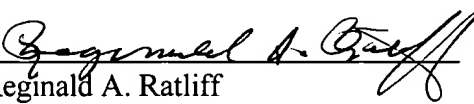
Conclusion

In light of the above-listed amendments and remarks, Applicants respectfully request allowance of the remaining Claims.

The Examiner is urged to contact Applicants' undersigned representative if the Examiner believes such action would expedite resolution of the present Application.

Respectfully submitted,  
WAGNER, MURABITO & HAO LLP

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Reginald A. Ratliff  
Registration No. 48,098  
Two North Market Street  
Third Floor  
San Jose, CA 95113  
(408) 938-9060